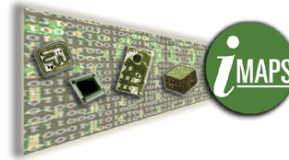


International Conference and Exhibition  
on  
**Device Packaging**

[www.imaps.org/devicepackaging](http://www.imaps.org/devicepackaging)

Radisson Fort McDowell Resort & Casino  
Scottsdale, Arizona - USA  
March 17 - 20, 2008



Sponsored by  
**IMAPS**

International Microelectronics And Packaging Society  
*Bringing Together the Entire Microelectronics Supply Chain!*

## Announcement and Call for Abstracts

Topical Workshop on

# **MEMS & Associated Microsystems**

*This workshop is being held as a part of the Device Packaging Conference*  
March 17 - 20, 2008

**Abstract Deadline: November 30, 2007**

### Technical Chairs:

**Robert Dean**, Auburn University  
Auburn, AL 36849  
Phone: 334-844-1838  
[rdean@eng.auburn.edu](mailto:rdean@eng.auburn.edu)

**Ajay P. Malshe**, University of Arkansas  
Fayetteville, AR 72701  
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### MEMS & Associated Microsystems Organizing Committee:

David Coe, PhD  
Ron Foster  
Brian Grantham, PE  
Matt Perry  
Keith Warren, PE

UAH  
Asept  
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### MEMS & Associated Microsystems Workshop Focus:

The objective of the MEMS & Associated Microsystems Workshop is to have a unique forum that brings together scientists, engineers, manufacturing, academia, and business people from around the world who have been working in the area of MEMS and associated microsystems. This workshop has been specifically organized to allow for the presentation and debate of some of the latest and hottest technologies related to fabrication, packaging and applications of MEMS devices.

### Abstracts are being requested on the following topics:

- MEMS Inertial Sensors
- MEMS RF Devices
- MEMS Sensors (non-inertial)
- Microfluidic and Bio-MEMS
- MEMS Reliability and Failure Analysis
- Optical MEMS (MOEMS)
- Multi-Sensor Integration
- MEMS Packaging and Testing
- Innovative Materials and Processing
- MEMS Operation in Harsh Environments
- Polymer and Laminated MEMS Devices
- System Integration of MEMS Devices
- Energy Scavenging
- Thermal Management Devices
- Near Hermetic MEMS Packaging
- Vacuum Packaging of MEMS Devices

Those wishing to present in the MEMS & Associated Microsystems Workshop sector of the Device Packaging Conference must submit a 200-300 word abstract electronically **no later than November 30, 2007**, using the on-line submittal form at: [www.imaps.org/abstracts.htm](http://www.imaps.org/abstracts.htm). Please contact Jackki Morris-Joyner by email at [jmorris@imaps.org](mailto:jmorris@imaps.org) or by phone at 305-382-8433 if you have questions.

### Device Packaging Exhibit and Technology Show:

IMAPS will hold a concurrent exhibition for vendors and suppliers who support the many aspects of MEMS Packaging. This venue features an ideal atmosphere to showcase your products and services to key decision making professionals in the industry. Full 8' by 10' exhibit spaces will be available. To reserve booth space please fill out the on-line submittal form before February 12, 2008 at: [www.imaps.org/devicepackaging](http://www.imaps.org/devicepackaging) or contact Ann Bell by email at [abell@imaps.org](mailto:abell@imaps.org) or by phone at 202-548-8717.

### Device Packaging Professional Development Courses (PDCs):

For those wishing to broaden their knowledge of device packaging, a selection of half-day courses will be offered on Monday, March 17<sup>th</sup>, preceding the technical conference. If you would like to participate as an instructor, please submit a description of your short course to Jackki Morris-Joyner by email at [jmorris@imaps.org](mailto:jmorris@imaps.org) **no later than November 30, 2007**.